

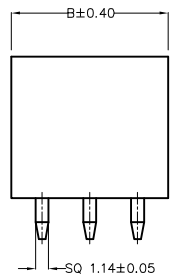
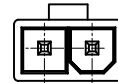
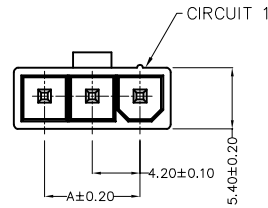
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1	△1	Size change	07/FEB/21	KATE	CHERRY
2	△2	Structure & Size change	27/JUL/22	MATT	CHERRY

Electrical

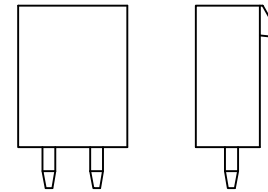
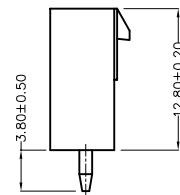
Current Rating: 9A AC(rms)/DC
Voltage Rating: 250V AC(rms)/DC
Contact Resistance: 15 mΩ Max
Insulation Resistance: 1000 MΩ MIN
Withstanding Voltage: 1500V AC r.m.s
Temperature Range-Operating: -25°C~+85°C

Material and Plating

Housing: PA66(UL 94V-2)
Contact Pin: Brass
Plating: Tin Plated



3-5Circuits



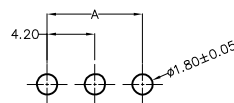
2Circuits

Circuits (n)	Part No.	Dimensions(in/mm)	
		A	B
2	FWF42006-S02S22TB	4.20	9.60
3	FWF42006-S03S22TB	8.40	13.80
4	FWF42006-S04S22TB	12.60	18.00
5	FWF42006-S05S22TB	16.80	22.20


Ordering Information

FWF 420 06 — S XX S 2 2 T B
1 2 3 4 5 6 7 8 9 10

1	Category FWF-Wafer	2	Series Number 420-Pitch4.2mm	3	Distinction No. 06	4	Row Option Single Row	5	Circuits XX	6	Entry Angle S-180° Vertical
7	Plating 2-Tin Plated	8	Material-Resin 2-PA66	9	Color-Resin T-Transparent	10	Packaging B-PE Bag				



Recommended P.C.Board Layout

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 28/JUN/13	PART NO. FWF42006-SXXS22TB	ITEM NO. FWF42006	 Leader Of Industry
	DESIGN UNITS Metric	X.±0.30	X'.±5'	CHECKED BY JACOB	DATE 28/JUN/13	TITLE Wire to Board (Wafer) Pitch 4.2mm 180° Vertical (DIP)	
SCALE 5:1	SIZE A4	X.XX±0.15	.XX'±1'	DRAWN BY CHERRY	DATE 28/JUN/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	